

Switch-mode Soft Recovery Power Rectifier MSR1560G, MSRF1560G

These state-of-the-art devices are designed for boost converter or hard-switched converter applications, especially for Power Factor Correction application. It could also be used as a free wheeling diode in variable speed motor control applications and switching mode power supplies.

Features

- Soft Recovery with Low Reverse Recovery Charge (Q_{RR}) and Peak Reverse Recovery Current (I_{RRM})
- Epoxy meets UL 94 V-0 @ 0.125 in
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb-Free Devices

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	600	V
Average Rectified Forward Current (At Rated V_R , $T_C = 125^{\circ}C$)	I _O	15	Α
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz,T _C = 125°C)	I _{FRM}	30	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	100	Α
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +150	°C

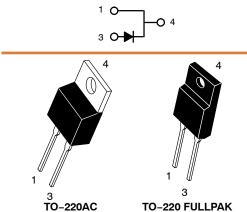
THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
MSR1560G: Thermal Resistance Junction-to-Case Junction-to-Ambient	$R_{ heta JC} \ R_{ heta JA}$	1.6 72.8	°C/W
MSRF1560G: Thermal Resistance Junction-to-Case Junction-to-Ambient	R _{θJC} R _{θJA}	4.25 75	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

SOFT RECOVERY POWER RECTIFIER 15 AMPERES, 600 VOLTS



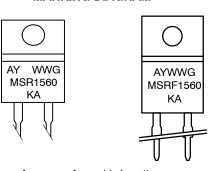
MARKING DIAGRAM

CASE 221AG

STYLE 1

CASE 221B

STYLE 1



A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package
KA = Diode Polarity

ORDERING INFORMATION

Device	Package	Shipping [†]
MSR1560G	TO-220AC (Pb-Free)	50 Units / Rail

DISCONTINUED (Note 1)

MSRF1560G	TO-220FP (Pb-Free)	50 Units / Rail
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- †For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
- DISCONTINUED: This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on www.onsemi.com.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Va	lue	Unit
Instantaneous Forward Voltage (Note 1) (I _F = 15 A)	V _F	T _J = 25°C	T _J = 150°C	V
Maximum Typical		1.8 1.5	1.4 1.2	
Instantaneous Reverse Current (V _R = 600 V)	I _R	T _J = 25°C	T _J = 150°C	μΑ
Maximum Typical		15 0.4	5000 100	
Reverse Recovery Time (Note 2) (V _R = 30 V, I _F = 1 A, di/dt = 100 A/μs)	t _{rr}	T _J = 25°C	T _J = 100°C	ns
Maximum Typical		45 35	65 54	
Typical Recovery Softness Factor ($V_R = 30 \text{ V}, I_F = 1 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$)	s = t _b /t _a	0.67	0.74	
Typical Peak Reverse Recovery Current (V _R = 30 V, I _F = 1 A, di/dt = 100 A/μs)	I _{RRM}	2.3	3.2	Α
Typical Reverse Recovery Charge (V _R = 30 V, I _F = 1 A, di/dt = 100 A/μs)	Q _{RR}	31	78	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2%

- 2. T_{RR} measured projecting from 25% of I_{RRM} to zero current

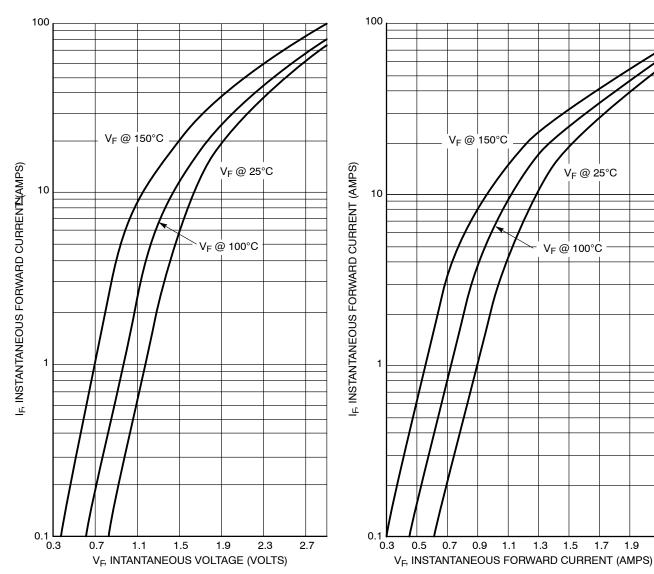


Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage

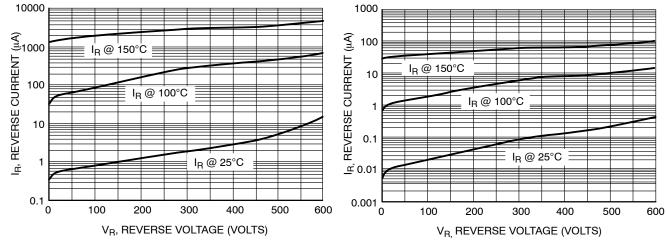
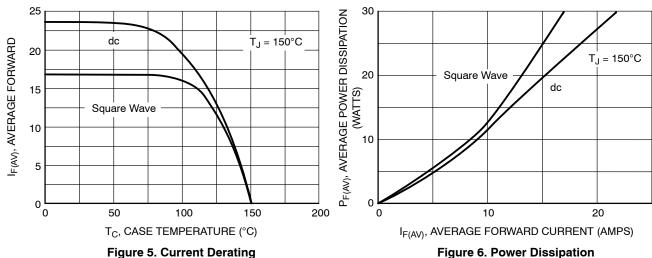


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current



 $T_J = 25^{\circ}C$

Figure 5. Current Derating

C, CAPACITANCE (pF)

 $T_J = 25^{\circ}C$ C, CAPACITANCE (pF)

V_R, REVERSE VOLTAGE (VOLTS) Figure 7. Maximum Capacitance

V_R, REVERSE VOLTAGE (VOLTS) Figure 8. Typical Capacitance

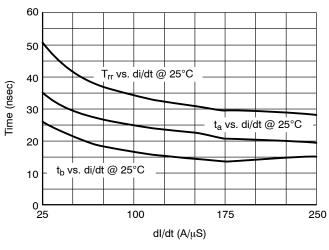


Figure 9. Typical Trr vs. di/dt

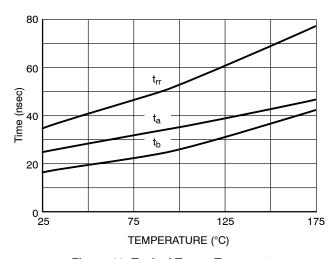


Figure 10. Typical Trr vs. Temperature

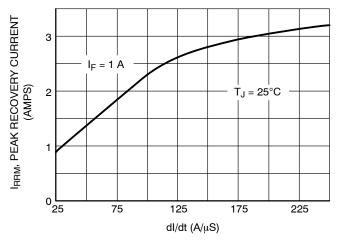


Figure 11. Typical Peak Reverse Recovery Current

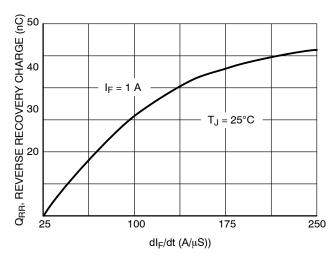


Figure 12. Typical Reverse Recovery Charge

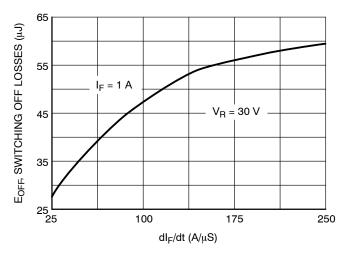


Figure 13. Typical Switching Off Losses

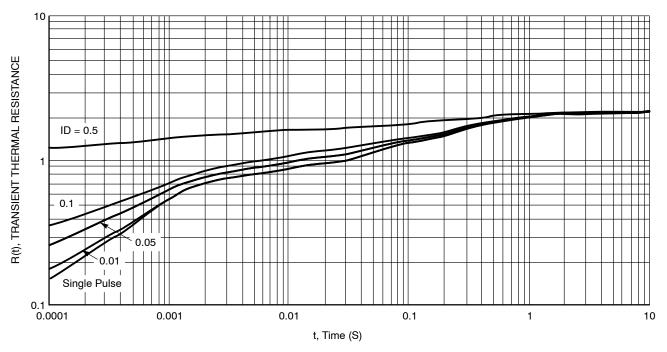


Figure 14. Transient Thermal Response

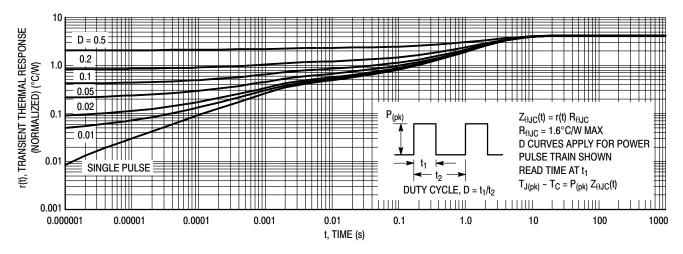


Figure 15. Thermal Response, (MSRF1560) Junction-to-Case ($R_{\theta JC}$)

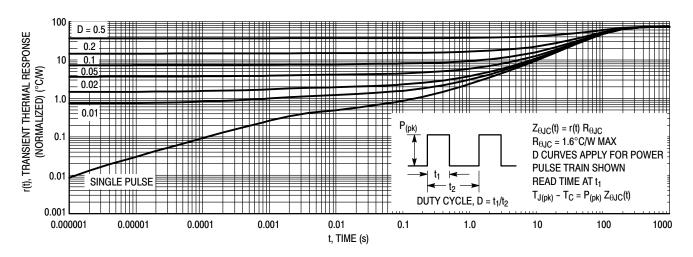
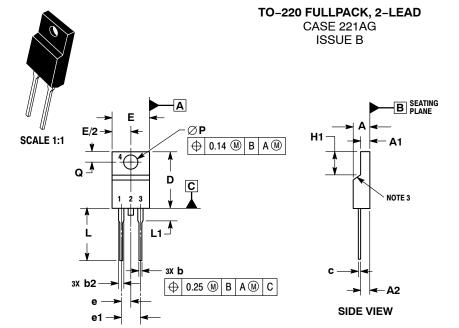
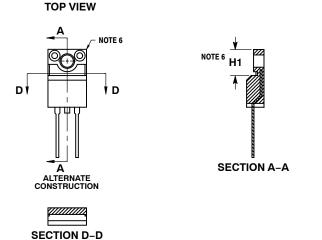


Figure 16. Thermal Response, (MSRF1560) Junction–to–Ambient ($R_{\theta JA}$)

DATE 27 AUG 2015



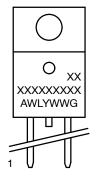




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. CONTOUR UNCONTROLLED IN THIS AREA.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH AND GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE TO BE MEASURED AT OUTERMOST EXTREME OF THE PLASTIC BODY.
- 5. DIMENSION b2 DOES NOT INCLUDE DAMBAR PROTRUSION. LEAD WIDTH INCLUDING PROTRUSION SHALL NOT EXCEED 2.00.

SHALL NOT EXCEED 2.0				
	MILLIMETERS			
DIM	MIN	MAX		
Α	4.30	4.70		
A1	2.50	2.90		
A2	2.50	2.90		
b	0.54	0.84		
b2	1.10	1.40		
c	0.49	0.79		
D	14.22	15.88		
Е	9.65	10.67		
е	2.54	BSC		
e1	5.08	BSC		
H1	6.40	6.90		
L	12.70	14.73		
L1		2.80		
P	3.00	3.40		
Q	2.80	3.20		

GENERIC MARKING DIAGRAM*



= Assembly Location

WL = Wafer Lot

= Year

WW = Work Week

G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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DESCRIPTION:	TO-220 FULLPACK, 2-LEAD		PAGE 1 OF 1	

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TO-220, 2-LEAD CASE 221B-04 **ISSUE F**

DATE 12 APR 2013

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.595	0.620	15.11	15.75
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.82
D	0.025	0.039	0.64	1.00
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
Н	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

Q Н

STYLE 1: PIN 1. CATHODE 2. N/A 3. ANODE

PIN 1. ANODE 2. N/A 3. CATHODE

4. ANODE

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